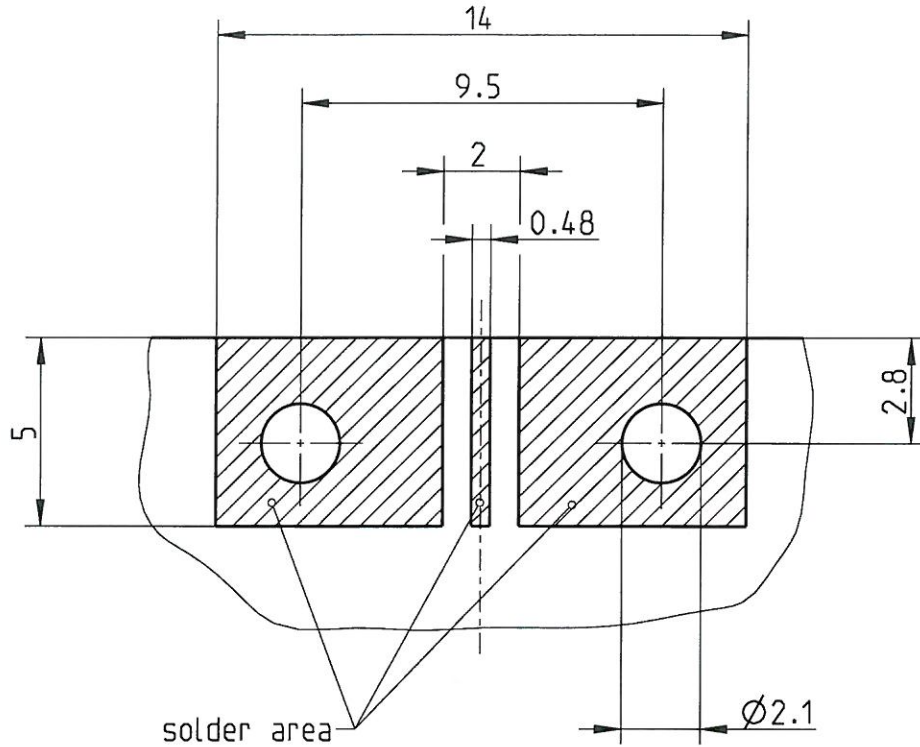


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Leiterplatten-Layout
PCB layout
B 208



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A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Format: TCC-FB-05-PE-AL-Einzelteil
Date: 16.11.2005
Version: 1.0

ISO-Projektion Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		scale: 5:1	weight(g): surface(mm²):
		date name drawn 16.11.2005 A_Nobis check. 30.11.05 <i>UJ</i> appr. 21/12/05 <i>UJ</i> dimensioning incl. finish		title: Leiterplatten-Layout PCB layout	
				part-no... MB_208	sheet: 1 of: 1
a00 rev. change-no	05-0615 name	A_Nobis date	16.11.2005 date	distribu- tion to:	FE AZ QSM RMT . X
				remarks: .	